

Evaluation board circuit diagram  
and implementation  
<MN63Y1208>

Ver 1.3

2013/10/10

Semiconductor Business Group  
Industrial Devices Company  
Panasonic Corporation

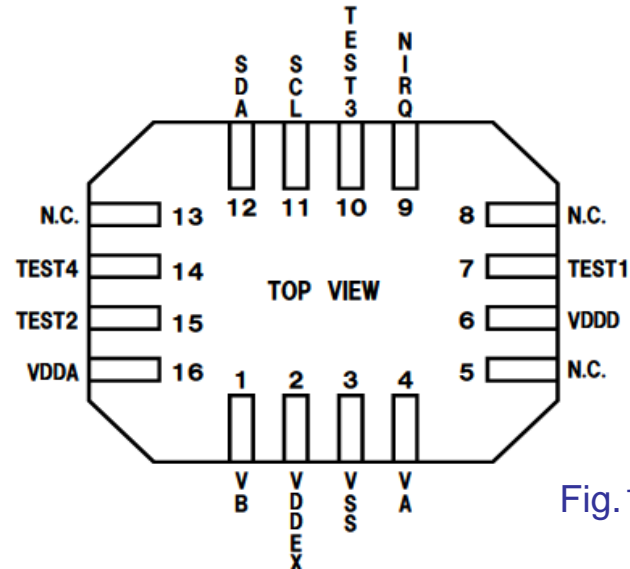


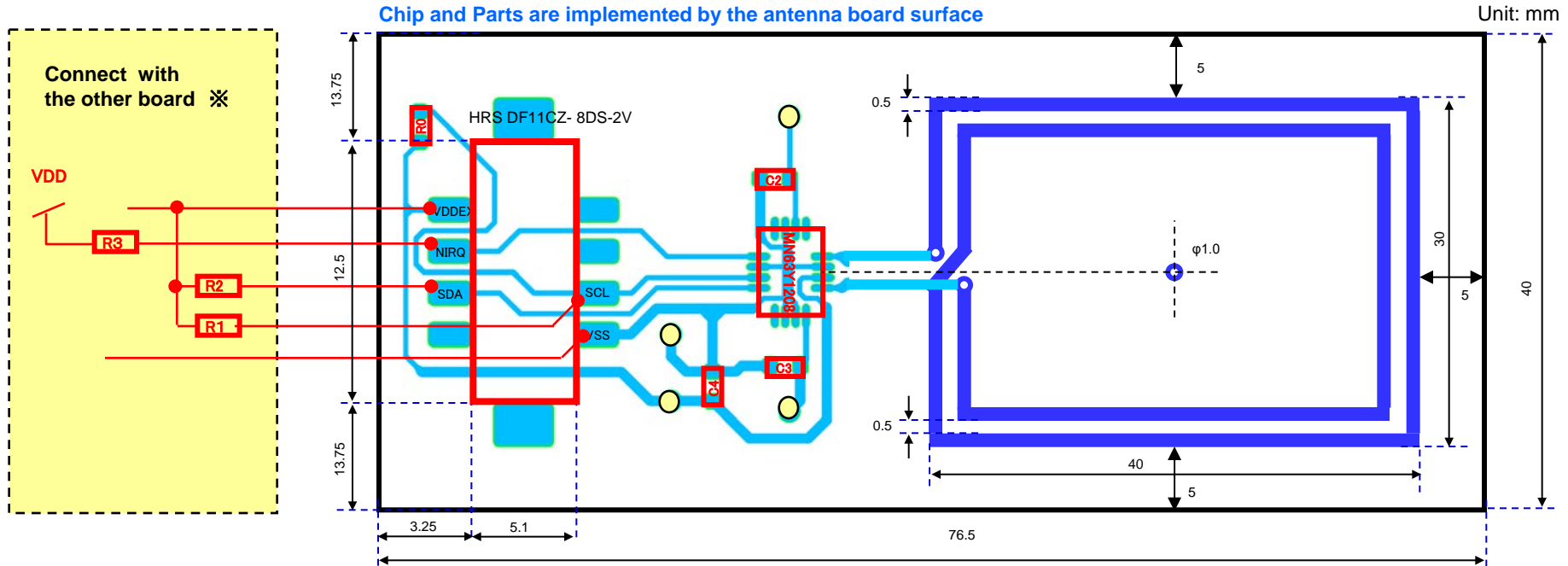
Fig.1 List of pin placement

Tab.1 Pins of the NFC tag

| PIN Number | Terminal name | Input/output | Input and output type | function  |
|------------|---------------|--------------|-----------------------|---|
| 1          | VB            | I/O          | —                     | Coil terminal   |
| 2          | VDDEX         | —            | Power                 | Power supply for contact (Input 1.7V ~ 3.6V)                    |
| 3          | VSS           | —            | GND                   | Ground  |
| 4          | VA            | I/O          | —                     | Coil terminal   |
| 5          | N.C.          | —            | —                     | Unconnected pin   |
| 6          | VDDD          | —            | Power                 | Digital internal power supply (Connect capacitance between VSS) |
| 7          | TEST1         | input        | —                     | Test control (Normally connected to VSS)                        |
| 8          | N.C.          | —            | —                     | Unconnected pin   |
| 9          | NIRQ          | output       | Open Drain            | Interrupt request output  |
| 10         | TEST3         | input        | —                     | Test control (Normally connected to VSS)                        |
| 11         | SCL           | input        | —                     | HOST I/F (I2C 100kHz)   |
| 12         | SDA           | I/O          | Open Drain            | HOST I/F (I2C 100kHz)   |
| 13         | N.C.          | —            | —                     | Unconnected pin   |
| 14         | TEST4         | input        | —                     | Test control (Normally connected to VSS)                        |
| 15         | TEST2         | input        | —                     | Test control (Normally connected to VSS)                        |
| 16         | VDDA          | —            | Power                 | Analog internal power supply (Connect capacitance between VSS)  |

# Figure of pattern of the evaluation board

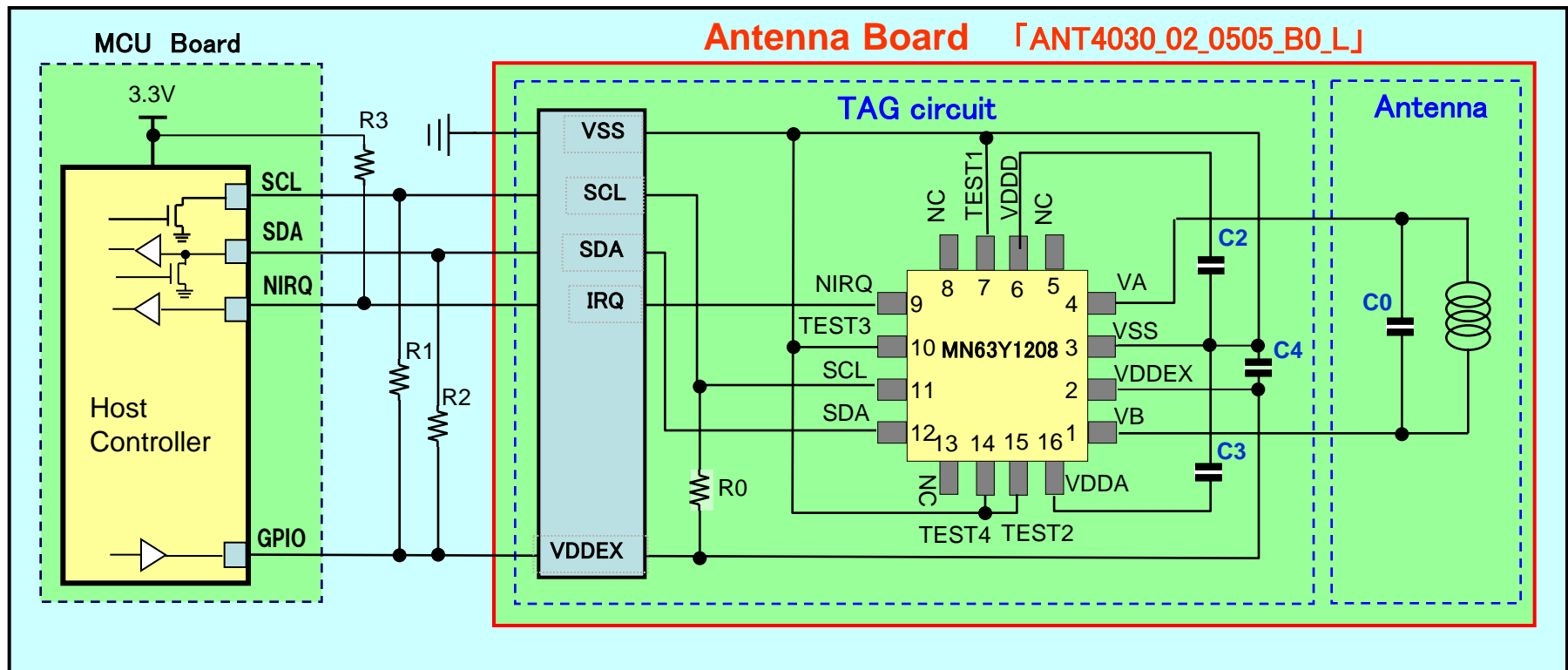
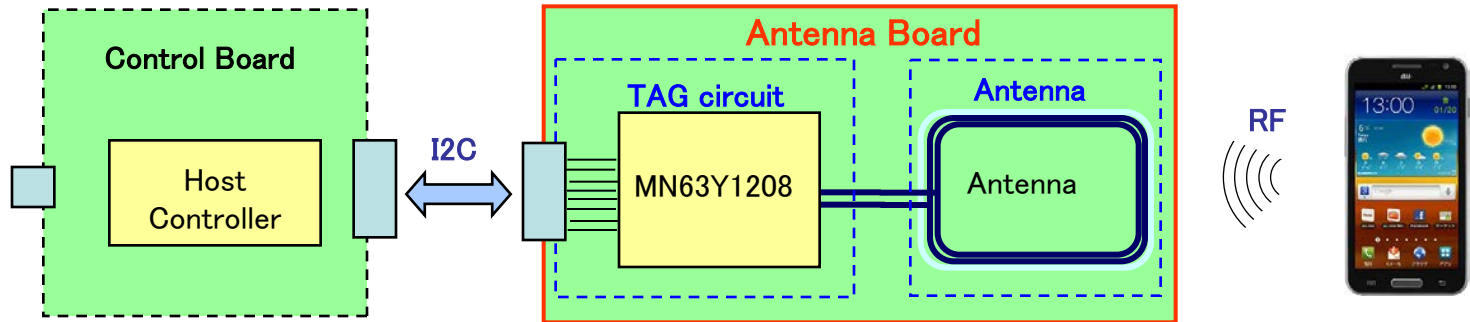
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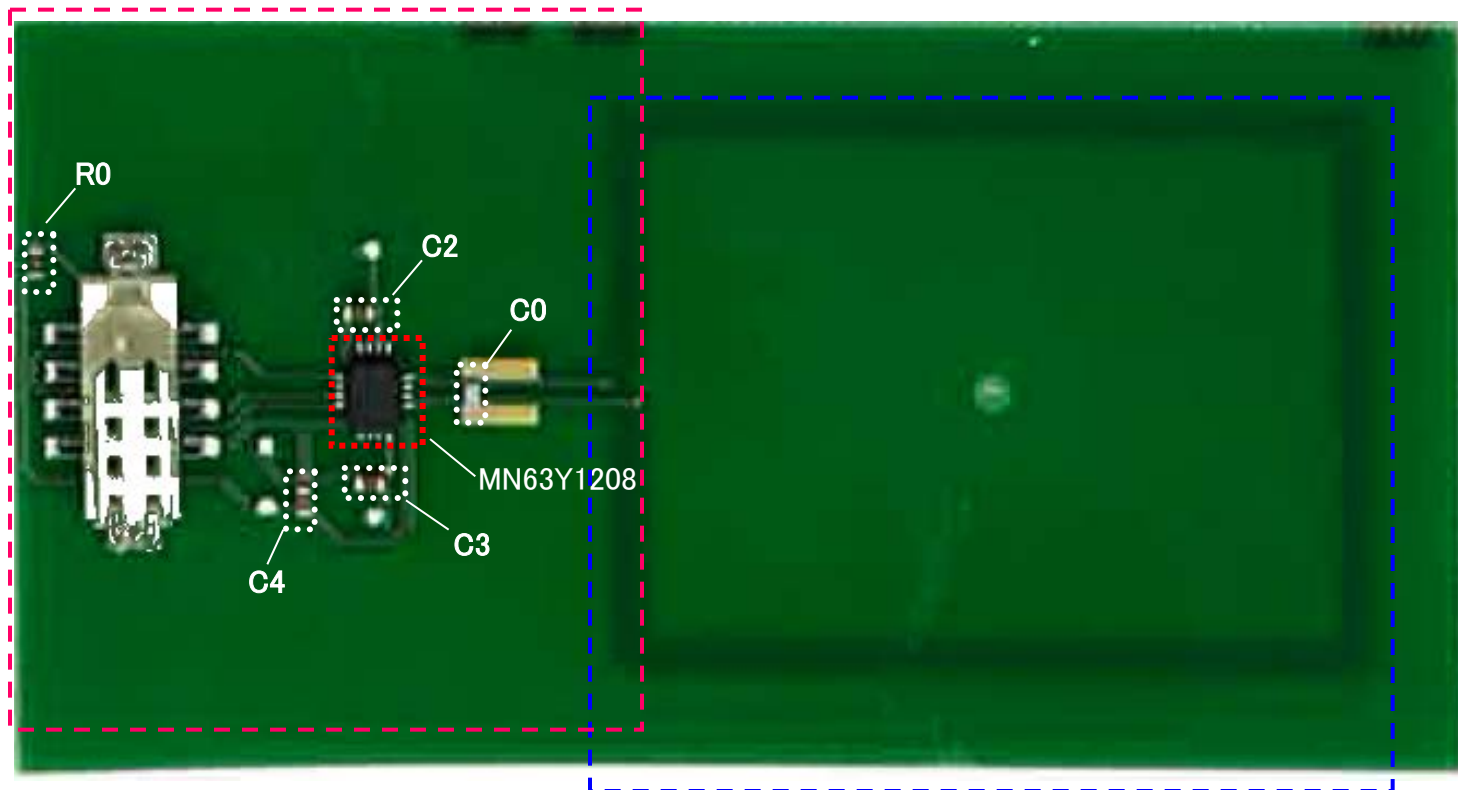
※ Substrate size may differ from the substrate which exists to a visitor.  
 ※ I connect pulling up resistance (R,R2,R3) to the microcomputer board of our offer.

| External part | Recommendation Value | Detailed explanation   |
|---------------|----------------------|--|
| R1,R2         | 3.3kΩ                | It is pulling up resistance for I2C signal lines. Please decide the resistance level in consideration of transmission rate, wiring capacity, current ability.<br>In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented. |
| R3            | 3.3kΩ                | It is pulling up resistance for interrupt signal lines.<br>Please decide the resistance level in consideration of wiring capacity, current ability.<br>In our NFC tag board "ANT4030_02_0505_B0_L," it is not implemented.           |
| C2, C3, C4    | 0.1μF                | It is a fixed value at the capacity between the power supply for operation stabilization of the tag LSI.<br>C2 is connected to VDDD, and C3 is connected to VDDA and C4 is connected to VDDEX  |
| R0            | 100kΩ                | It is pulling up resistance to prevent an uncertainty state of SCL causing the malfunction.<br>When NFC tag LSI has the terms of use that R1 is not connected to, I am necessary.  |

### NFC tag system constitution

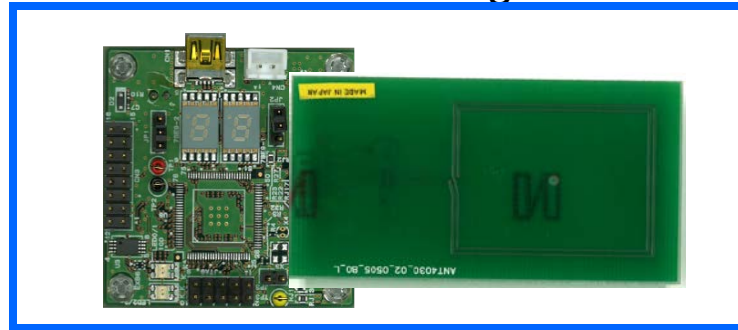


Chip and Parts are implemented by the board surface

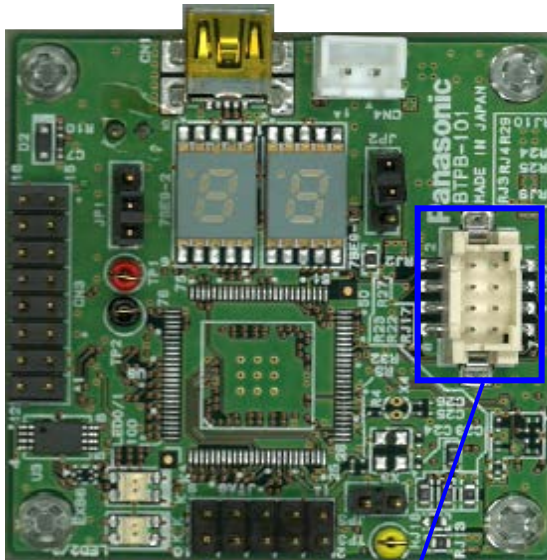


Antenna is implemented by the board back side

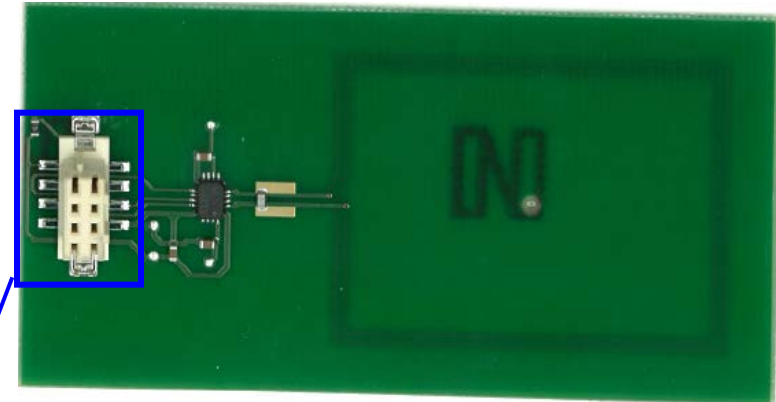
## Connection image



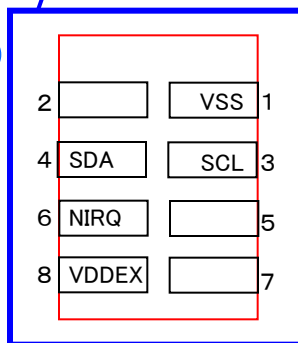
Micon Board [BTPB101-B]



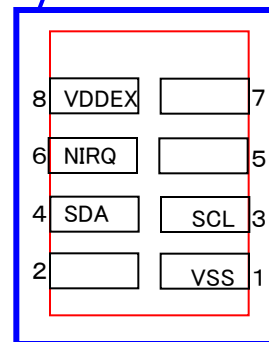
Antenna Board [ANT4030\_02\_0505\_B0\_L]



DF11CZ-8DP-2V(27)  
(Hirose Electric)



HRS DF11CZ- 8DS-2V  
(Hirose Electric)



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